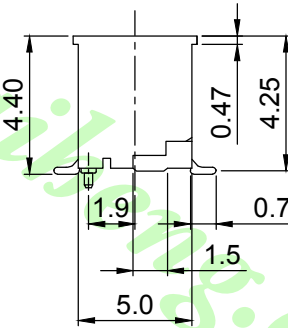
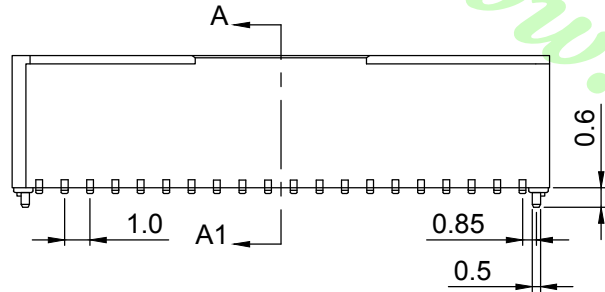
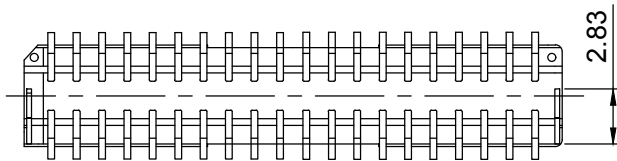


RECOMMENDED P.C. BOARD PATTERN DIM.



See: A-A1



Circuits	Dimension mm		Part No.
	A	B	
2×10	9.0	12.3	LW-SHD100S-2×10-SP
2×15	14.0	17.3	LW-SHD100S-2×15-SP
2×20	19.0	22.3	LW-SHD100S-2×20-SP
2×25	24.0	27.3	LW-SHD100S-2×25-SP

## SPECIFICATIONS

### Electrical

Voltage Rating: 50VAC DC

Current Rating: 1.0A AC DC

Contact Resistance: Initial value/20mΩ max;  
After environmental testing/40mΩ max.

Insulation Resistance: 100MΩ min.

Temperature Range: -25°C ~ +85°C.

Withstanding voltage: 500V AC/minute.

### Material and Finish

Header Contact: Phosphor Bronze,  
Nickel-undercoated, Tin-Plated.

Wafer: Glass-filled polyamide, UL94V-0.

Color: Natural (Ivory).

Solder Tad: Brass, Copper-undercoated, Tin-plated.

			公差/UNLESS OTHERWISE SPECIFIED TOLERANCES ARE	單位/Unit mm	品名(Title):
A0	NEW DRAWING	2018.08.09	.XX ±0.2	比例/Scale Free	1.0mm Wire to Board Wafer SMT 180°, Dual Row, Peg
REV	概述/REVISION	日期/DATE	.X ±0.3	料號/Part No:	LW-SHD100S-2×XX-SP






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 REV: A0